

LM98714

*LM98714 Three Channel, 16-Bit, 45 MSPS Digital Copier Analog Front End
with Integrated CCD/CIS Sensor Timing Generator and LVDS Output*



Literature Number: SNAS254

LM98714

Three Channel, 16-Bit, 45 MSPS Digital Copier Analog Front End with Integrated CCD/CIS Sensor Timing Generator and LVDS Output

General Description

The LM98714 is a fully integrated, high performance 16-Bit, 45 MSPS signal processing solution for digital color copiers, scanners, and other image processing applications. High-speed signal throughput is achieved with an innovative architecture utilizing Correlated Double Sampling (CDS), typically employed with CCD arrays, or Sample and Hold (S/H) inputs (for Contact Image Sensors and CMOS image sensors). The signal paths utilize 8 bit Programmable Gain Amplifiers (PGA), a +/-9-Bit offset correction DAC and independently controlled Digital Black Level correction loops for each input. The PGA and offset DAC are programmed independently allowing unique values of gain and offset for each of the three inputs. The signals are then routed to a 45MHz high performance analog-to-digital converter (ADC). The fully differential processing channel shows exceptional noise immunity, having a very low noise floor of -74dB. The 16-bit ADC has excellent dynamic performance making the LM98714 transparent in the image reproduction chain.

Applications

- Multi-Function Peripherals
- Facsimile Equipment
- Flatbed or Handheld Color Scanners
- High-speed Document Scanner

Features

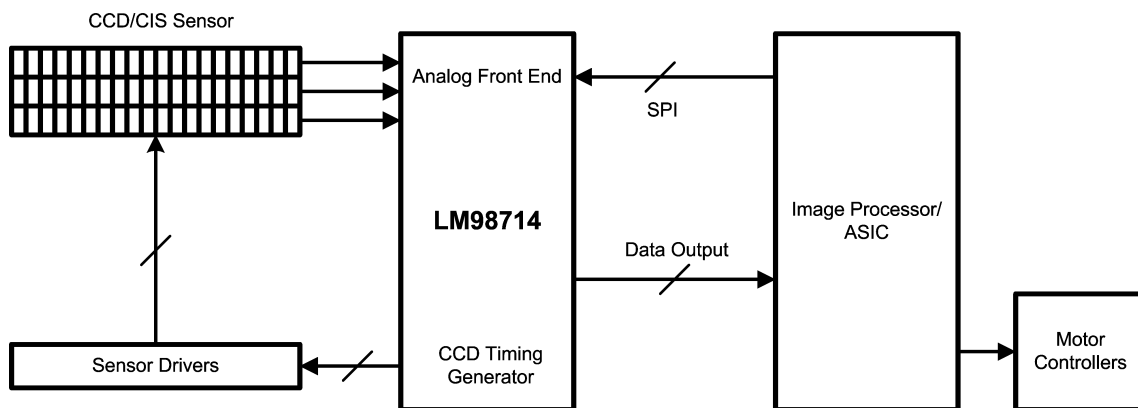
- LVDS/CMOS Outputs
- LVDS/CMOS Pixel Rate Input Clock or ADC Input Clock
- CDS or S/H Processing for CCD or CIS sensors

- Independent Gain/Offset Correction for Each Channel
- Digital Black Level Correction Loop for Each Channel
- Programmable Input Clamp Voltage
- Flexible CCD/CIS Sensor Timing Generator

Key Specifications

■ Maximum Input Level	1.2 or 2.4 Volt Modes (both with + or - polarity option)
■ ADC Resolution	16-Bit
■ ADC Sampling Rate	45 MSPS
■ INL	+/- 23 LSB (typ)
■ Channel Sampling Rate	15/22.5/30 MSPS
■ PGA Gain Steps	256 Steps
■ PGA Gain Range	0.7 to 7.84x
■ Analog DAC Resolution	+/-9 Bits
■ Analog DAC Range	+/-300mV or +/-600mV
■ Digital DAC Resolution	+/-6 Bits
■ Digital DAC Range	-1024 LSB to + 1008 LSB
■ SNR	-74dB (@0dB PGA Gain)
■ Power Dissipation	505mW (LVDS) 610mW (CMOS)
■ Operating Temp	0 to 70°C
■ Supply Voltage	3.3V Nominal (3.0V to 3.6V range)

System Block Diagram



LM98714 - Three Channel, 16-Bit, 45 MSPS Digital Copier Analog Front End with Integrated CCD/CIS Sensor Timing Generator and LVDS Output

20105370

LM98714 Overall Chip Block Diagram

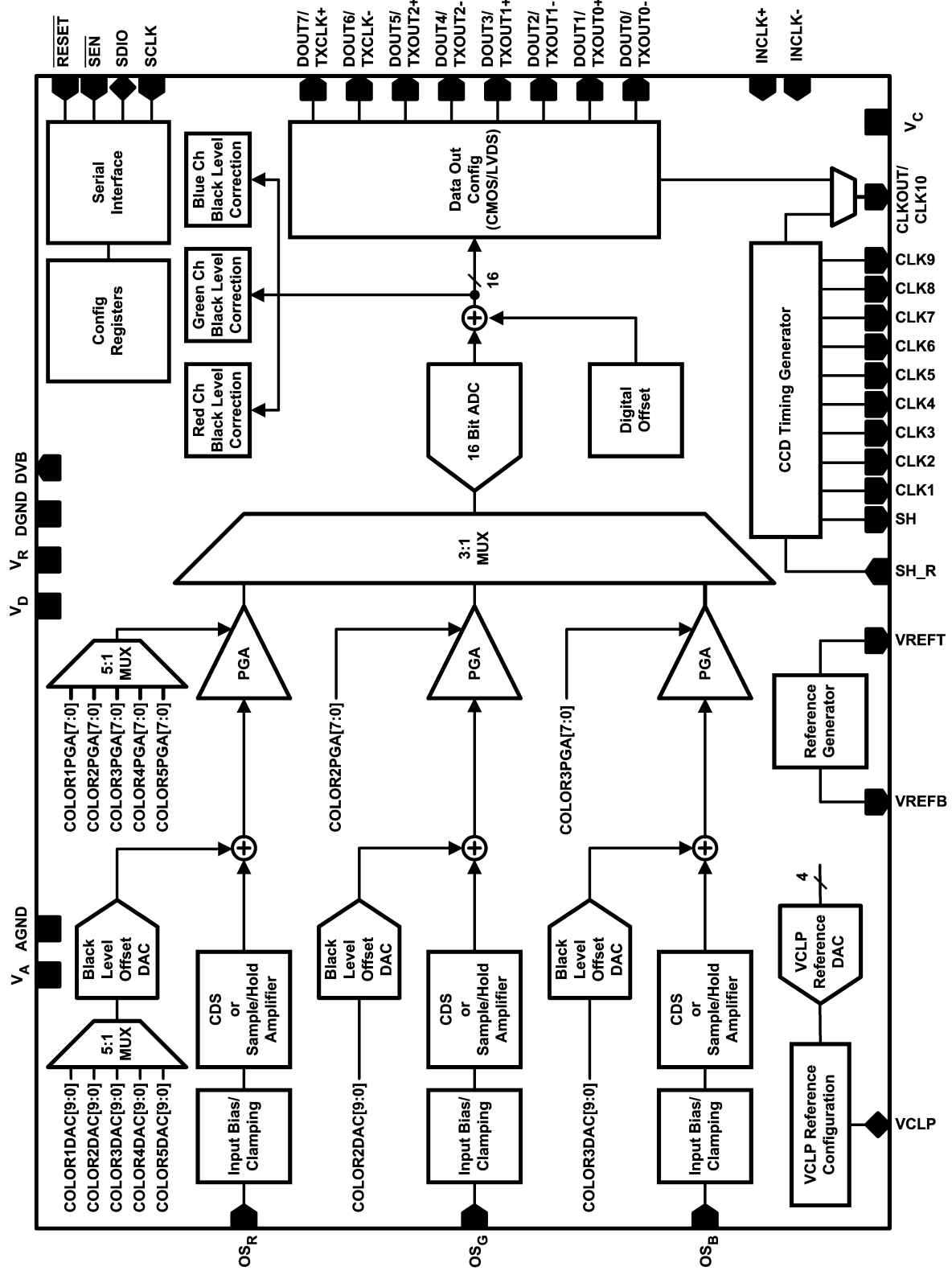
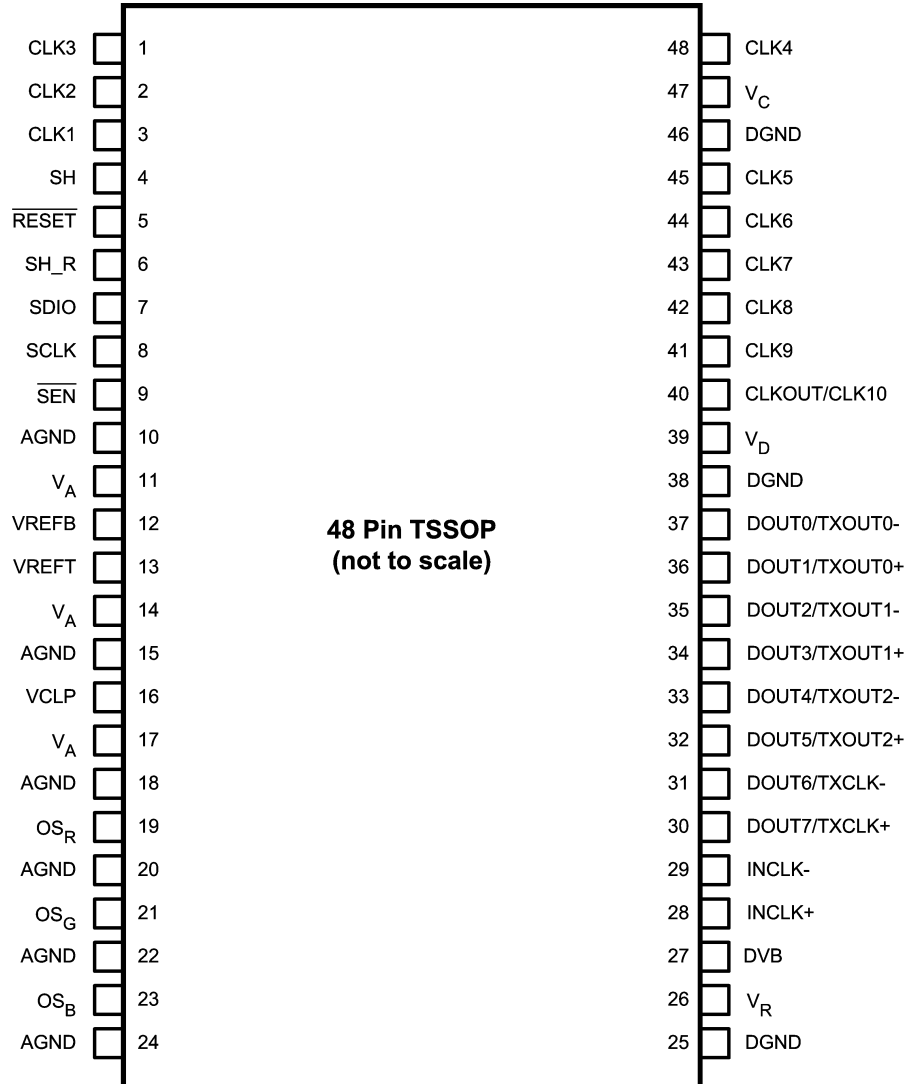


FIGURE 1. Chip Block Diagram

20105301

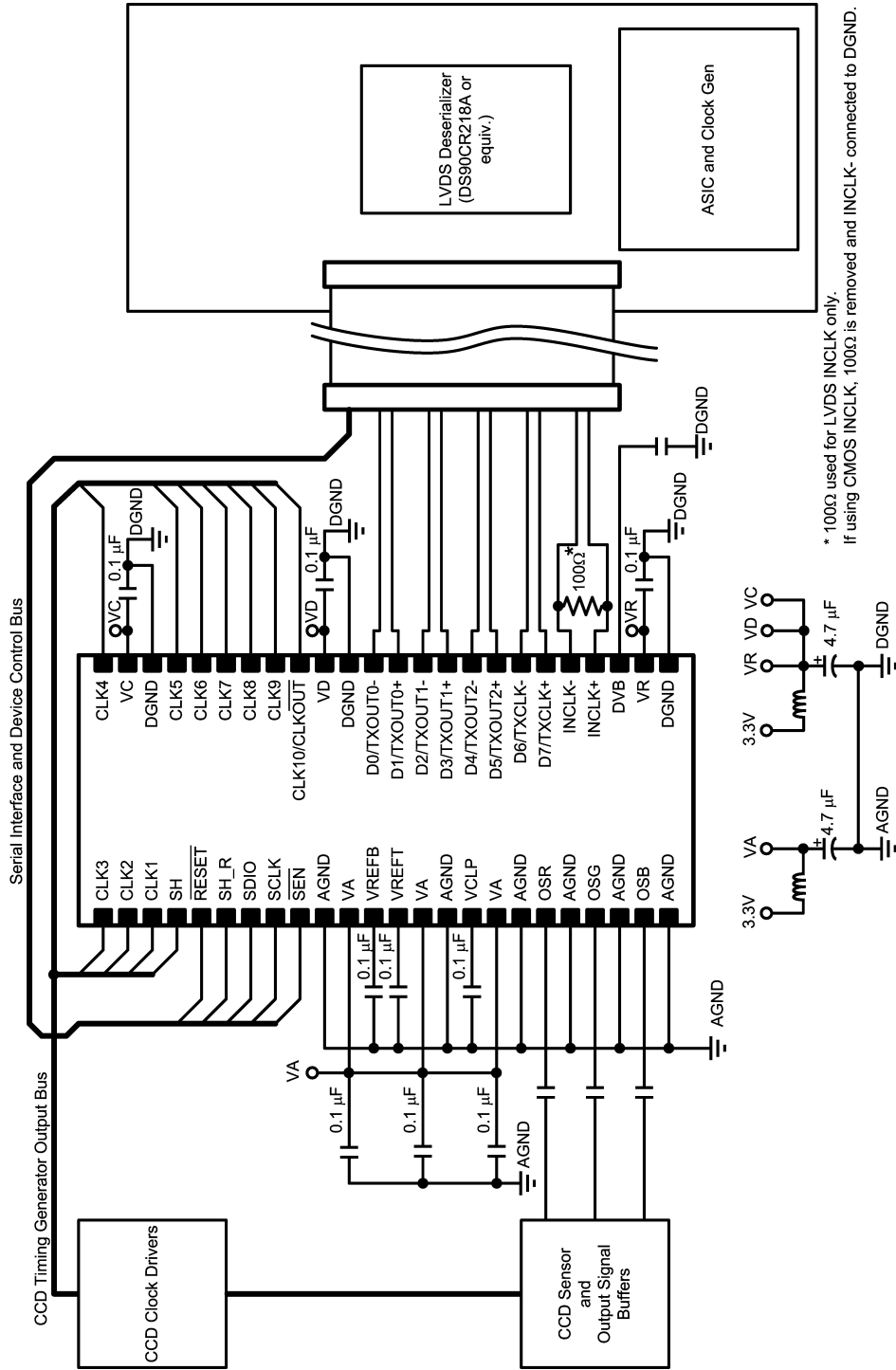
LM98714 Pin Out Diagram



20105302

FIGURE 2. LM98714 Pin Out Diagram

Typical Application Diagram



* 100Ω used for LVDS INCLK only.
If using CMOS INCLK, 100Ω is removed and INCLK- connected to DGND.

20105373

FIGURE 3. Typical Application Diagram

Pin Descriptions

Pin	Name	I/O	Typ	Res	Description
1	CLK3	O	D	PU	Configurable sensor control output.
2	CLK2	O	D	PD	Configurable sensor control output.
3	CLK1	O	D	PU	Configurable sensor control output.
4	SH	O	D	PD	Sensor - Shift or transfer control signal for CCD and CIS sensors.
5	$\overline{\text{RESET}}$	I	D	PU	Active-low master reset. NC when function not being used.
6	SH_R	I	D	PD	External request for an SH pulse.
7	SDIO	I/O	D		Serial Interface Data Input
8	SCLK	I	D	PD	Serial Interface shift register clock.
9	$\overline{\text{SEN}}$	I	D	PU	Active-low chip enable for the Serial Interface.
10	AGND		P		Analog ground return.
11	V _A		P		Analog power supply. Bypass voltage source with 4.7 μ F and pin with 0.1 μ F to AGND.
12	VREFB	O	A		Bottom of ADC reference. Bypass with a 0.1 μ F capacitor to ground.
13	VREFT	O	A		Top of ADC reference. Bypass with a 0.1 μ F capacitor to ground.
14	V _A		P		Analog power supply. Bypass voltage source with 4.7 μ F and pin with 0.1 μ F to AGND.
15	AGND		P		Analog ground return.
16	VCLP	IO	A		Input Clamp Voltage. Normally bypassed with a 0.1 μ F, and a 4.7 μ F capacitor to AGND. An external reference voltage may be applied to this pin.
17	V _A		P		Analog power supply. Bypass voltage source with 4.7 μ F and pin with 0.1 μ F to AGND.
18	AGND		P		Analog ground return.
19	OS _R	I	A		Analog input signal. Typically sensor Red output AC-coupled thru a capacitor.
20	AGND		P		Analog ground return.
21	OS _G	I	A		Analog input signal. Typically sensor Green output AC-coupled thru a capacitor.
22	AGND		P		Analog ground return.
23	OS _B	I	A		Analog input signal. Typically sensor Blue output AC-coupled thru a capacitor.
24	AGND		P		Analog ground return.
25	DGND		P		Digital ground return.
26	V _R		P		Power supply input for internal voltage reference generator. Bypass this supply pin with a 0.1 μ F capacitor.
27	DVB	O	P		Digital Core Voltage bypass. Not an input. Bypass with 0.1 μ F capacitor to DGND.
28	INCLK+	I	D		Clock Input. Non-Inverting input for LVDS clocks or CMOS clock input. CMOS clock is selected when pin 29 is held at DGND, otherwise clock is configured for LVDS operation.
29	INCLK-	I	D		Clock Input. Inverting input for LVDS clocks, connect to DGND for CMOS clock.
30	DOUT7/ TXCLK+	O	D		Bit 7 of the digital video output bus in CMOS Mode, LVDS Frame Clock+ in LVDS Mode.
31	DOUT6/ TXCLK-	O	D		Bit 6 of the digital video output bus in CMOS Mode, LVDS Frame Clock- in LVDS Mode.
32	DOUT5/ TXOUT2+	O	D		Bit 5 of the digital video output bus in CMOS Mode, LVDS Data Out2+ in LVDS Mode.
33	DOUT4/ TXOUT2-	O	D		Bit 4 of the digital video output bus in CMOS Mode, LVDS Data Out2- in LVDS Mode.
34	DOUT3/ TXOUT1+	O	D		Bit 3 of the digital video output bus in CMOS Mode, LVDS Data Out1+ in LVDS Mode.
35	DOUT2/ TXOUT1-	O	D		Bit 2 of the digital video output bus in CMOS Mode, LVDS Data Out1- in LVDS Mode.

Pin Descriptions (Continued)

Pin	Name	I/O	Typ	Res	Description
36	DOUT1/ TXOUT0+	O	D		Bit 1 of the digital video output bus in CMOS Mode, LVDS Data Out0+ in LVDS Mode.
37	DOUT0/ TXOUT0-	O	D		Bit 0 of the digital video output bus in CMOS Mode, LVDS Data Out0- in LVDS Mode.
38	DGND		P		Digital ground return.
39	V _D		P		Power supply for the digital circuits. Bypass this supply pin with 0.1μF capacitor. A single 4.7μF capacitor should be used between the supply and the VD, VR and VC pins.
40	CLKOUT/ CLK10	O	D	PD	Output clock for registering output data when using CMOS outputs, or configurable sensor control output.
41	CLK9	O	D	PD	Configurable sensor control output.
42	CLK8	O	D	PD	Configurable sensor control output.
43	CLK7	O	D	PD	Configurable sensor control output.
44	CLK6	O	D	PU	Configurable sensor control output.
45	CLK5	O	D	PD	Configurable sensor control output.
46	DGND		P		Digital ground return.
47	V _C		P		Power supply for the sensor control outputs. Bypass this supply pin with 0.1μF capacitor.
48	CLK4	O	D	PD	Configurable sensor control output.

(I=Input), (O=Output), (IO=Bi-directional), (P=Power), (D=Digital), (A=Analog), (PU=Pull Up with an internal resistor), (PD=Pull Down with an internal resistor).

Absolute Maximum Ratings (Notes 2,

1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (VA,VR,VD,VC)	4.2V
Voltage on Any Input Pin (Not to exceed 4.2V)	-0.3V to (VA + 0.3V)
Voltage on Any Output Pin (except DVB and not to exceed 4.2V)	-0.3V to (VA + 0.3V)
DVB Output Pin Voltage	2.0V
Input Current at any pin other than Supply Pins (Note 3)	±25 mA
Package Input Current (except Supply Pins) (Note 3)	±50 mA
Maximum Junction Temperature (TA)	150°C

Thermal Resistance (θ_{JA})	66°C/W
Package Dissipation at $T_A = 25^\circ\text{C}$ (Note 4)	1.89W
ESD Rating (Note 5)	
Human Body Model	2500V
Machine Model	250V
Storage Temperature	-65°C to +150°C
<i>Soldering process must comply with National Semiconductor's Reflow Temperature Profile specifications. Refer to www.national.com/packaging.</i>	
(Note 6)	

Operating Ratings (Notes 1, 2)

Operating Temperature Range	0°C ≤ T_A ≤ +70°C
All Supply Voltage	+3.0V to +3.6V

Electrical Characteristics

The following specifications apply for VA = VD = VR = VC = 3.3V, CL = 10pF, and fINCLK = 15MHz unless otherwise specified. **Boldface limits apply for TA = TMIN to TMAX;** all other limits TA = 25°C.

Symbol	Parameter	Conditions	Min	Typ (Note 8)	Max	Units
CMOS Digital Input DC Specifications (RESETb, SH_R, SCLK, SENb)						
V _{IH}	Logical "1" Input Voltage		2.0			V
V _{IL}	Logical "0" Input Voltage				0.8	V
I _{IH}	Logical "1" Input Current	V _{IH} = VD RESET SH_R, SCLK SEN		235 70 130		nA μA nA
I _{IL}	Logical "0" Input Current	V _{IL} = DGND RESET SH_R, SCLK SEN		70 235 70		μA nA μA
CMOS Digital Output DC Specifications (SH, CLK1 to CLK10, CMOS Data Outputs)						
V _{OH}	Logical "1" Output Voltage	I _{OUT} = -0.5mA	2.95			V
V _{OL}	Logical "0" Output Voltage	I _{OUT} = 1.6mA			0.25	V
I _{OS}	Output Short Circuit Current	V _{OUT} = DGND V _{OUT} = VD		16 -20		mA
I _{OZ}	CMOS Output TRI-STATE Current	V _{OUT} = DGND V _{OUT} = VD		20 -25		nA
CMOS Digital Input/Output DC Specifications (SDIO)						
I _{IH}	Logical "1" Input Current	V _{IH} = VD		90		nA
I _{IL}	Logical "0" Input Current	V _{IL} = DGND		90		nA
LVDS/CMOS Clock Receiver DC Specifications (INCLK+ and INCLK- Pins)						
V _{IHL}	Differential LVDS Clock High Threshold Voltage	R _L = 100W V _{CM} (LVDS Input Common Mode Voltage) = 1.25V			100	mV
V _{ILL}	Differential LVDS Clock Low Threshold Voltage		-100			mV

Electrical Characteristics (Continued)

The following specifications apply for $V_A = V_D = V_R = V_C = 3.3V$, $C_L = 10pF$, and $f_{INCLK} = 15MHz$ unless otherwise specified. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	Min	Typ (Note 8)	Max	Units
V_{IHC}	CMOS Clock High Threshold Voltage	INCLK- = DGND	2.0			V
V_{ILC}	CMOS Clock Low Threshold Voltage				0.8	V
I_{IHL}	CMOS Clock Input High Current				280	μA
I_{ILC}	CMOS Clock Input Low Current				-150	μA
LVDS Output DC Specifications						
V_{OD}	Differential Output Voltage	$R_L = 100\Omega$	180	328	450	mV
V_{OS}	LVDS Output Offset Voltage		1.17	1.23	1.3	V
I_{OS}	Output Short Circuit Current	$V_{OUT} = 0V, R_L = 100\Omega$		7.9		mA
Power Supply Specifications						
IA	VA Analog Supply Current	VA Normal State	60	97	125	mA
		VA Low Power State (Powerdown)	12	23	32	mA
IR	VR Digital Supply Current	VR Normal State (LVDS Outputs)	30	64	75	mA
		CMOS Output Data Format	15	47	55	mA
		LVDS Output Data Format with Data Outputs Disabled		47		mA
ID	VD Digital Output Driver Supply Current	LVDS Output Data Format		0.05		mA
		CMOS Output Data Format (ATE Loading of CMOS Outputs > 50pF)	12		40	mA
IC	VC CCD Timing Generator Output Driver Supply Current	Typical sensor outputs: SH, CLK1= Φ 1A, CLK2= Φ 2A, CLK3= Φ B, CLK4= Φ C, CLK5=RS, CLK6=CP (ATE Loading of CMOS Outputs > 50pF)	0.5		12	mA
PWR	Average Power Dissipation	LVDS Output Data Format	350	505	650	mW
		CMOS Output Data Format (ATE Loading of CMOS Outputs > 50pF)	380	610	700	mW
Input Sampling Circuit Specifications						
V_{IN}	Input Voltage Level	CDS Gain=1x, PGA Gain=1x CDS Gain=2x, PGA Gain=1x		2.3 1.22		Vp-p

Electrical Characteristics (Continued)

The following specifications apply for $V_A = V_D = V_R = V_C = 3.3V$, $C_L = 10pF$, and $f_{INCLK} = 15MHz$ unless otherwise specified. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	Min	Typ (Note 8)	Max	Units
I_{IN_SH}	Sample and Hold Mode Input Leakage Current	Source Followers Off CDS Gain = 1x $OS_X = VA$ ($OS_X = AGND$)	50 (-70)		70 (-40)	μA
		Source Followers Off CDS Gain = 2x $OS_X = VA$ ($OS_X = AGND$)	75 (-105)		105 (-75)	μA
		Source Followers On CDS Gain = 2x $OS_X = VA$ ($OS_X = AGND$)	-200	-10 -16	200	nA
C_{SH}	Sample/Hold Mode Equivalent Input Capacitance (see Figure 11)	CDS Gain = 1x		2.5		pF
		CDS Gain = 2x		4		pF
I_{IN_CDS}	CDS Mode Input Leakage Current	Source Followers Off $OS_X = VA$ ($OS_X = AGND$)	-300	7 (-25)	300	nA
R_{CLPIN}	CLPIN Switch Resistance (OS_X to VCLP Node in Figure 8)			16	50	Ω
VCLP Reference Circuit Specifications						
	VCLP DAC Resolution			4		Bits
	VCLP DAC Step Size			0.16		V
V_{VCLP}	VCLP DAC Voltage Min Output	VCLP Config. Register = 0001 0000b	0.14	0.26	0.43	V
	VCLP DAC Voltage Max Output	VCLP Config. Register = 0001 1111b	2.38	2.68	2.93	V
	Resistor Ladder Enabled	VCLP Config. Register = 0010 xxxxb	1.54	$V_A / 2$	1.73	V
I_{SC}	VCLP DAC Short Circuit Output Current	VCLP Config. Register = 0001 xxxxb		30		mA
Black Level Offset DAC Specifications						
	Resolution			10		Bits
	Monotonicity		Guaranteed by characterization			
	Offset Adjustment Range Referred to AFE Input	CDS Gain = 1x Minimum DAC Code = 0x000 Maximum DAC Code = 0x3FF		-614 614		mV
		CDS Gain = 2x Minimum DAC Code = 0x000 Maximum DAC Code = 0x3FF		-307 307		mV
	Offset Adjustment Range Referred to AFE Output	Minimum DAC Code = 0x000 Maximum DAC Code = 0x3FF	-16000 16000		-18200 18200	LSB
	DAC LSB Step Size	CDS Gain = 1x Referred to AFE Output		1.2 (32)		mV (LSB)
DNL	Differential Non-Linearity		-0.95		3.25	LSB

Electrical Characteristics (Continued)

The following specifications apply for $V_A = V_D = V_R = V_C = 3.3V$, $C_L = 10pF$, and $f_{INCLK} = 15MHz$ unless otherwise specified. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	Min	Typ (Note 8)	Max	Units
INL	Integral Non-Linearity		-3.1		2.65	LSB
PGA Specifications						
	Gain Resolution			8		Bits
	Monotonicity		Guaranteed by characterization			
	Maximum Gain	CDS Gain = 1x	7.18	7.9	8.77	V/V
		CDS Gain = 1x	17.1	17.9	18.9	dB
	Minimum Gain	CDS Gain = 1x	0.56	0.7	0.82	V/V
		CDS Gain = 1x	-5	-3	-1.72	dB
	PGA Function	Gain (V/V) = (196/(280-PGA Code)) Gain (dB) = 20LOG10(196/(280-PGA Code))				
	Channel Matching	Minimum PGA Gain		3		%
		Maximum PGA Gain		12.7		
ADC Specifications						
V_{REFT}	Top of Reference			2.07		V
V_{REFB}	Bottom of Reference			0.89		V
$V_{REFT} - V_{REFB}$	Differential Reference Voltage		1.07	1.18	1.29	V
	Overrange Output Code			65535		
	Underrange Output Code			0		
Digital Offset "DAC" Specifications						
	Resolution			7		Bits
	Digital Offset DAC LSB Step Size	Referred to AFE Output		16		LSB
	Offset Adjustment Range Referred to AFE Output	Min DAC Code = 7b0000000		-1024		LSB
		Mid DAC Code = 7b1000000		0		
		Max DAC Code = 7b1111111		1008		
Full Channel Performance Specifications						
DNL	Differential Non-Linearity		-0.99	0.8/-0.6	2.55	LSB
INL	Integral Non-Linearity		-73	+/-23	78	LSB
SNR	Total Output Noise	Minimum PGA Gain		-79		dB
				7.2		LSB RMS
		PGA Gain = 1x		-74		dB
				13	30	LSB RMS
		Maximum PGA Gain		-56		dB
				104		LSB RMS
	Channel to Channel Crosstalk	Mode 3		47		LSB
		Mode 2		16		

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions. Operation of the device beyond the Operating Ratings is not recommended.

Note 2: All voltages are measured with respect to AGND = DGND = 0V, unless otherwise specified.

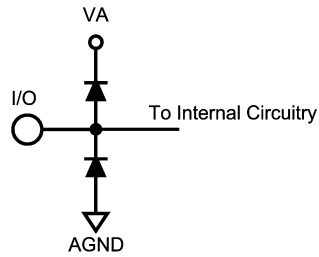
Note 3: When the input voltage (V_{IN}) at any pin exceeds the power supplies ($V_{IN} < GND$ or $V_{IN} > V_A$ or V_D), the current at that pin should be limited to 25 mA. The 50 mA maximum package input current rating limits the number of pins that can simultaneously safely exceed the power supplies with an input current of 25 mA to two.

Note 4: The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX} , θ_{JA} and the ambient temperature, T_A . The maximum allowable power dissipation at any temperature is $P_D = (T_{JMAX} - T_A)/\theta_{JA}$. The values for maximum power dissipation listed above will be reached only when the device is operated in a severe fault condition (e.g. when input or output pins are driven beyond the power supply voltages, or the power supply polarity is reversed). Such conditions should always be avoided.

Note 5: Human body model is 100 pF capacitor discharged through a 1.5 k Ω resistor. Machine model is 220 pF discharged through 0 Ω .

Note 6: Reflow temperature profiles are different for lead-free and non-lead-free packages.

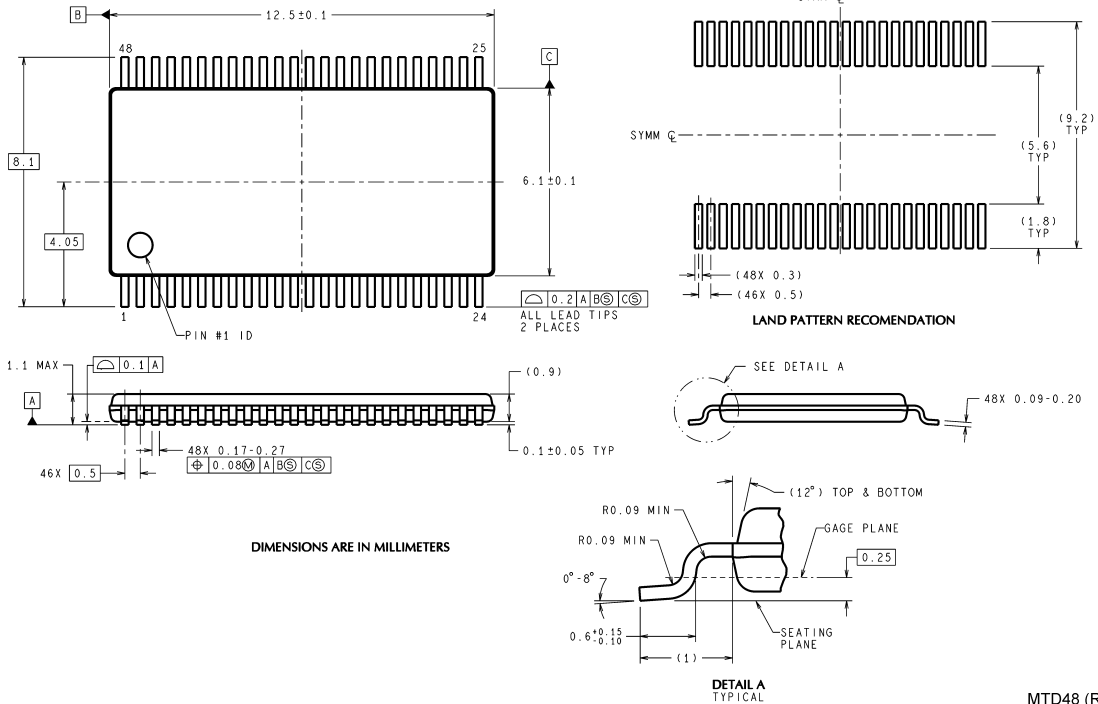
Note 7: The analog inputs are protected as shown below. Input voltage magnitudes beyond the supply rails will not damage the device, provided the current is limited per note 3. However, input errors will be generated if the input goes above V_A and below $AGND$.



20105371

Note 8: Typical figures are at $T_A = 25^\circ\text{C}$, and represent most likely parametric norms at the time of product characterization. The typical specifications are not guaranteed.

Physical Dimensions inches (millimeters) unless otherwise noted



**48-Lead TSSOP
 NS Package Number MTD48**

MTD48 (Rev E)

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.

For the most current product information visit us at www.national.com.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

BANNED SUBSTANCE COMPLIANCE

National Semiconductor follows the provisions of the Product Stewardship Guide for Customers (CSP-9-111C2) and Banned Substances and Materials of Interest Specification (CSP-9-111S2) for regulatory environmental compliance. Details may be found at: www.national.com/quality/green.

Lead free products are RoHS compliant.

National Semiconductor
 Americas Customer
 Support Center
 Email: new.feedback@nsc.com
 Tel: 1-800-272-9959

National Semiconductor
 Europe Customer Support Center
 Fax: +49 (0) 180-530 85 86
 Email: europe.support@nsc.com
 Deutsch Tel: +49 (0) 69 9508 6208
 English Tel: +44 (0) 870 24 0 2171
 Français Tel: +33 (0) 1 41 91 8790

National Semiconductor
 Asia Pacific Customer
 Support Center
 Email: ap.support@nsc.com

National Semiconductor
 Japan Customer Support Center
 Fax: 81-3-5639-7507
 Email: jpn.feedback@nsc.com
 Tel: 81-3-5639-7560

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated